

## CLAIMS

1. A CMP pad comprising an outermost layer that differs from the rest of pad beneath said outermost layer.
2. A CMP pad of claim 1, wherein said pad is made of polyurethane or polyurethane composites.
3. A CMP pad of claim 1, wherein the thickness of said outermost layer is at least 0.05 micron.
4. A CMP pad according to claim 1, wherein said outermost layer is produced by subjecting the surface of the finished, as manufactured pad to electromagnetic radiation, selected from the group of EB, UV and IR.
5. A CMP pad according to claim 4, wherein the bulk material of the pad comprises radiation-sensitive compounds.
6. A CMP pad according to claim 1, wherein said outermost layer is produced by applying a layer or film onto the pad, such layer or film being designed to improve its CMP performance.
7. A CMP pad according to claim 6, wherein said layer is sensitive to heat or radiation.
8. A CMP pad according to claim 6, wherein said outermost layer is made of a metal, metal oxide, metal alloy, or metal comprising compound, capable to reduce galvanic attack of copper interconnects.

9. A CMP pad according to claim 8, wherein said outermost layer is made of  $\text{Cu}_2\text{O}$ ,  $\text{CuO}$ , finely divided Cu metal powder,  $\text{SnO}$ ,  $\text{SnO}_2$ , finely divided tin metal and combinations thereof.
10. A CMP pad according to claim 1 being a slurry-delivering pad.
11. A CMP pad according to claim 1, being a fixed abrasive pad.